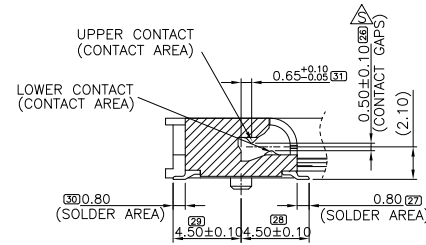
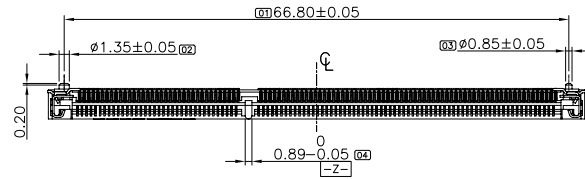


GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2015/11/02	Phebe Su

SECTION A-A
SCALE 2:1

NOTES:

1. MATERIAL:

1.1 HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL94V-0;
COLOR: SEE NOTES6.

1.2 CONTACTS: COPPER ALLOY

1.3 LATCH: STAINLESS STEEL

1.4 FLOATING PEG: STAINLESS STEEL

2. FINISH:

2.1 CONTACT:

GOLD (SEE TABLE) PLATED ON CONTACT AREA AND GOLD 2u"
SOLDER AREA. 50u" MIN. NICKEL UNDERPLATING.

2.2 FLOATING PEG:

GOLD FLASH PLATED ON SOLDERING AREA.
50u" MIN. NICKEL UNDERPLATING.

3. REFLOW SOLDER CAPABLE TO 260°C.

4. SHOULD BE MEASURED BY CPK

5. MAKED " " DIMENSIONS NEED BE CONTROLLED IN FAI.

PART NUMBER:

MDDR3-204XX06

Series number

PLATING CODE:

1: GOLD FLASH 4: Au15u"

2: Au5u" 5: Au20u"

3: Au10u" 6: Au30u"

MARK & HSG COLOR:

0: DDR3 STD 1.5V & BLACK

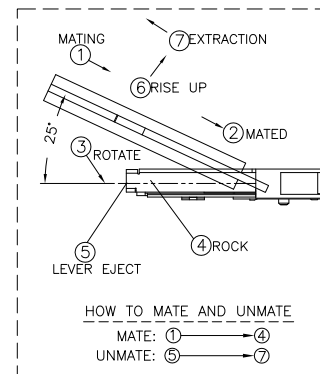
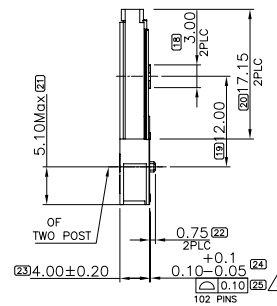
1: DDR3 STD & BLACK 2: STD & BLACK

3: DDR3 STD 1.5V & IVORY

4: DDR3 STD & IVORY 5: STD & IVORY

PIN NUMBER CODE:

204: 204 PINS

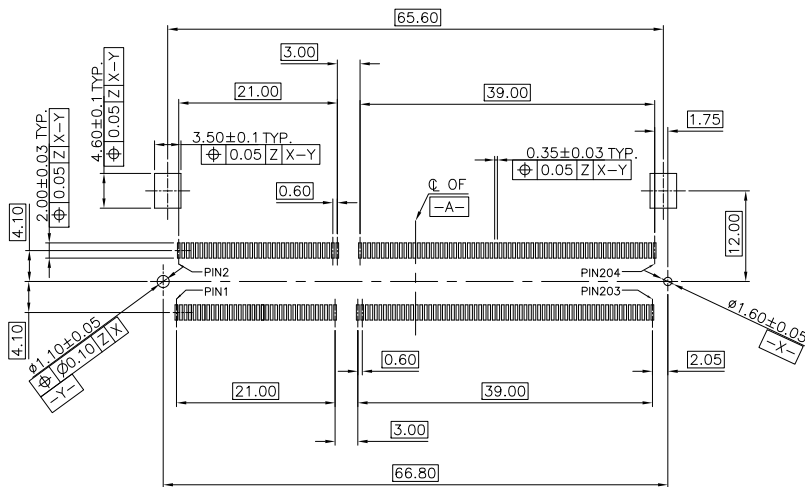


HOW TO MATE AND UNMATE

MATE: ① → ④

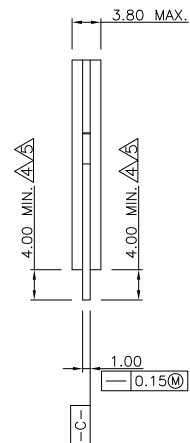
UNMATE: ⑤ → ⑦

RECOMMENDED PCB LAYOUT



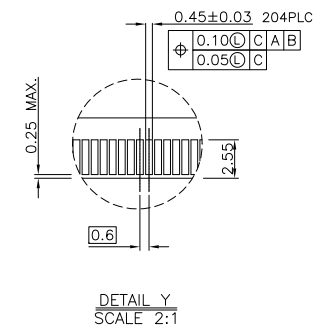
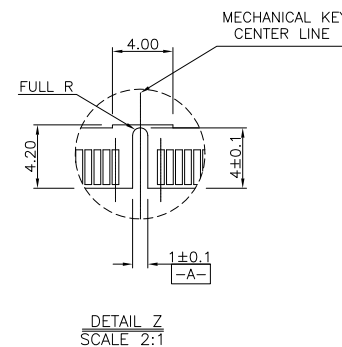
NO	VARIETY	QTY	METERIAL	REMARK
 Matrix Electronics Co.,Ltd				
TOLERANCE: X:X ±0.25 X:XX ±0.15 X:XXX ±0.10 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2015/11/02	PART NAME: DDR3 SO DIMM 4.0H STD ASSY
CHECKED BY: Vicky Hsieh		DATE : 2015/11/02	PART NO.	MDDR3-204XX06
APPROVED BY1: Richard Hsieh		DATE : 2015/11/02	MOLD NO.	NA
APPROVED BY2: Richard Hsieh		DATE : 2015/11/02	DRAW NO.	
SCALE:1:1 SIZE:A4			SHEET NO.	1 OF 2

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
AO			Initial	2015/11/02	Phebe Su



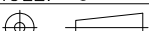
NOTE:

1. TOLERANCES ON ALL DIMENSIONS ± 0.15 UNLESS OTHERWISE SPECIFIED.
2. P.C.BOARD THICKNESS APPLIES ACROSS TABS AND INCLUDES PLATING AND/OR MENTAIZATION.
3. FINISH OF PAD:GOLD PLATING 0.00076MIN OVER Ni PLATING 0.002MIN.
4. DIMENSIONS APPLICABLE WHEN COMPONENTS MOUNTED ON BOTH SIDE. PCB THICKNESS NOT TO BE EXCEEDED OUTSIDE OF COMPONENT AREA.
5. BORDER OF COMPONENT AREA.
6. REFER TO JEDEC SPEC. MO-268 FOR COMPLETE MODULE.



30.00	CA
31.75	BA
25.40	AA
DIM. A	SDRAM VARIATIONS

RECOMMENDED MATING P.C.B CONFIGURATION

NO	VARIETY	QTY	MATERIAL	REMARK
 Matrix Electronics Co.,Ltd				
TOLERANCE: X.X X.XX ±0.25 X.XXX ±0.15 X.XXXX ±0.10 ANGLE: ±3°		DESIGN BY : Phebe Su	DATE : 2015/11/02	PART NAME: DDR3 SO DIMM 4.0H STD ASSY
		CHECKED BY: Vicky Hsieh	DATE : 2015/11/02	PART NO. MDDR3-204XX06
		APPROVED BY1: Richard Hsieh	DATE : 2015/11/02	MOLD NO. NA
UNIT: mm [inch]		APPROVED BY2: Richard Hsieh	DATE :	DRAW NO.
SCALE:1:1	SIZE:A4	Richard Hsieh	2015/11/02	SHEET NO. 2 OF 2